

# Automotive Electronics Council

## Component Technical Committee

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# Agenda

*(subject to change)*

**2008 - Thirteenth Annual  
Automotive Electronics  
Reliability Workshop**

**May 6, 7, & 8**

**Novi, MI  
Sheraton Detroit Novi Hotel**

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Exhibit 1020  
PGR2017-00010  
AVX CORPORA

**Tuesday, May 6, 2008**

**7:30 am - 8:00 am Continental Breakfast (provided)**

**8:00 am - 8:20 am Workshop Introductions**

<b>Session 1:</b> <b>Passive/Electro-Mechanical Issues</b> <b>8:20 am - 10:25 am</b>	<b>1A.1</b>	8:20 am - 8:45 am	Ron Demcko <i>AVX</i>	FlexiSafe MLCC Termination Device
	<b>1A.2</b>	8:45 am - 9:10 am	Kazuo Kasue <i>Murata</i>	Investigation of the Environmental Components for TPSM
	<b>1A.3</b>	9:10 am - 9:35 am	Reiner Kuehl <i>Vishay BComponents</i>	Advance Properties of Thin Film Resistor for High Reliability and Better Performance
	<b>1A.4</b>	9:35 am - 10:00 am	Ron Demcko <i>AVX</i>	Multilayer Varistor Performance in Automotive Applications
	<b>1A.5</b>	10:00 am - 10:25 am	Michael Azarian <i>University of Maryland (CALCE)</i>	Reliability of Flexible Termination Components in High Temperature-Humidity-Bias Conditions

**10:25 am - 10:45 am BREAK: Coffee, drinks, snacks (provided)**

**Breakout Session 10:45 am - 12:50 pm Q200 Document Review & Discussion**

<b>Session 2:</b> <b>Discrete Semiconductor Issues</b> <b>10:45 pm - 12:50 pm</b>	<b>2A.1</b>	10:45 am - 11:10 am	Arthur Chiang <i>Vishay Siliconix</i>	Backside Emission Microscopy for Power MOSFETs
	<b>2A.2</b>	11:10 am - 11:35 am	Harold Anderson <i>ON Semiconductor</i>	Copper Wire Bond: A Comprehensive Characterization
	<b>2A.3</b>	11:35 am - 12:00 am	Romeo Letor <i>STMicroelectronics</i>	New Spiked Gate Stress for Robust MOSFET in the Automotive Environment
	<b>2A.4</b>	12:00 am - 12:25 am	Nishad Patil <i>University of Maryland (CALCE)</i>	Failure Precursors for Insulated Gate Transistors
	<b>2A.5</b>	12:25 pm - 12:50 pm	Arthur Chiang <i>Vishay Siliconix</i>	ESD Characterization of Trench Power MOSFETs

**12:50 am - 2:15 pm LUNCH (on own)**

**Tuesday, May 6, 2008 (continued)**

<b>Session 3:</b> <b>General Component Issues</b> <b>2:15 pm - 3:30 pm</b>	<b>3A.1</b>	2:15 pm - 2:40 pm	Michael Azarian <i>University of Maryland (CALCE)</i>	Organizational Reliability Capability Manufacturers
	<b>3A.2</b>	2:40 pm - 3:05 pm	Sony Mathew <i>University of Maryland (CALCE)</i>	Prognostics and Health Monitoring
	<b>3A.3</b>	3:05 pm - 3:30 pm	Gerold Will <i>Continental</i>	Automotive Component Quality Re
<b>BREAK: coffee, drinks, snacks (provided)</b>				
<b>Session 4:</b> <b>Zero Defects (Part 1)</b> <b>3:50 pm - 5:05 pm</b>	<b>4A.1</b>	3:50 pm - 4:15 pm	Yael Cohen <i>OptimalTest</i>	Outlier Management Solution
	<b>4A.2</b>	4:15 pm - 4:40 pm	Justin Judkins <i>Ridgetop</i>	Die-Level Process Monitors Provide Level Parameters and Performance
	<b>4A.3</b>	4:40 pm - 5:05 pm	Stephen Pateras <i>LogicVision</i>	The Embedded Path to Zero Defec
<b>DINNER (on own)</b>				
<b>AEC Panel Discussion</b>		5:05 pm - 7:00 pm		
		7:00 pm - 9:00 pm		<b>Q101 Document Review &amp; Discussion</b>

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**Wednesday, May 7, 2008**

**Continental Breakfast (provided)**

7:30 am - 8:00 am

<b>Session 5: Pb-Free Issues 8:00 am - 9:15 am</b>	5A.1	8:00 am - 8:25 am	Sony Mathew <i>University of Maryland (CALCE)</i>	Lead-Free Electronics: Tin Whisker
	5A.2	8:25am - 8:50am	Min Ding <i>Freescale</i>	Sn3.5Ag and Sn3.8Ag0.7Cu Pb-free Application on Ni-Au Finish
	5A.3	8:50 am - 9:15 am	Hiroshi Yamashita <i>NEC Electronics</i>	Tin Whisker Growth Evaluation on s
<b>Session 6: Zero Defects (Part 2) 9:15 am - 10:05 am</b>	6A.1	9:15 am - 9:40 am	Kuo-tung Cheng <i>TSMC</i>	In-Situ Process Variation and Outli
	6A.2	9:40 am - 10:05 am	Ruby Clark <i>Freescale</i>	Zero Defects Implementation-Holist Environment

**BREAK: Coffee, drinks, snacks (provided)**

10:05 am - 10:25 am

<b>Session 7: Zero Defects (Part 3) 10:25 am - 11:15 am</b>	7A.1	10:25 am - 10:50 am	Dileepan Narayanan <i>Cypress</i>	Analysis of Wafer Bin Map Patterns Customer Returns
	7A.2	10:50 am - 11:15 am	James Williams <i>Texas Instruments</i>	Zero Defects Launch Approach
<b>Session 8: Packaging Issues 11:15 am - 12:30 pm</b>	8A.1	11:15 am - 11:40 am	Mike Varnau <i>Delphi Corporation</i>	Characterization of BGA Warpage i
	8A.2	11:40 am - 12:05 pm	Galen Lin <i>Integrated Silicon Solution Inc. (ISSI)</i>	A Study on the Relationship between Device Performance in Function an
	8A.3	12:05 pm - 12:30 pm	Daniel Vanderstraeten <i>ON Semiconductor</i>	Impact of Mold compound Filler Pa Thermomechanical Stress Variation

**LUNCH (on own)**

12:30 pm - 2:00 pm

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**Wednesday, May 7, 2008 (continued)**

<b>Session 9: Failure Analysis 2:15 pm - 3:30 pm</b>	<b>9A.1</b>	2:00 pm - 2:25 pm	Eric Bedes <i>NEC Electronics America</i>	Failure Analysis Techniques for Ma
	<b>9A.2</b>	2:25pm - 2:50pm	Mike Azarian <i>University of Maryland (CALCE)</i>	RF Impedance Analysis for Reliabl
	<b>9A.3</b>	2:50 pm - 3:15 pm	Yizi Xing <i>NXP Semiconductors</i>	Fast Fault Diagnosis for Analog IC's
	<b>9A.4</b>	3:15 pm - 3:40 pm	Michael Wiebemeit <i>NEC Electronics Europe GmbH</i>	FIB Assisted EMI and OBIRCH Ana

3:40 pm - 4:00 pm

**BREAK: Coffee, drinks, snacks (provided)**

<b>Session 10: Electrostatic Discharge 4:00 pm - 5:50 pm</b>	<b>10A.1</b>	4:00 pm - 4:25 pm	Michal Polewski <i>NXP Semiconductors</i>	Comparison of JEDEC and Q100 S CDM Calibration Issues
	<b>10A.2</b>	4:25 pm - 4:50 pm	K.T. Kaschani <i>Atmel</i>	The Significance of the Machine Mo Integrated Circuits
	<b>10A.3</b>	4:50 pm - 5:50 pm	Charvaka Duvury (et al) <i>Texas Instruments</i>	Proposal for the Reduction of ESD Participation)

5:50 pm - 7:30 pm

**DINNER (on own)**

<b>AEC Panel Discussion</b>	7:30 pm - 9:00 pm	<b>Q100 Document Review &amp; Discussion</b>
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